

## PMP10129 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C4, C10	3	0.1uF	B32921C3104M	EPCOS Inc	CAP, Film, 0.1 μF, 305 V, +/- 20%, TH	13x6x12mm
C2	1	0.22uF	B32653A224J	EPCOS Inc	CAP, Film, 0.22 μF, 1000 V, +/- 5%, TH	26.50x20.50x11mm
C3, C9	2	68uF	EKXG401ELL680MM25S	Chemi-Con	CAP, AL, 68 μF, 400 V, +/- 20%, ohm, TH	D18xL31.5mm
C5	1	1500pF	C3216C0G2J152J	TDK	CAP, CERM, 1500 pF, 630 V, +/- 5%, C0G/NP0, 1206	1206
C6	1	100uF	EEE-FK1H101P	Panasonic	CAP, AL, 100 μF, 50 V, +/- 20%, 0.34 ohm, SMD	SMT Radial F
C7, C8	2	10uF	C3225X7R1H106M250AC	TDK	CAP, CERM, 10 μF, 50 V, +/- 20%, X7R, 1210	1210
C11	1	470uF	EEE-FK1A471P	Panasonic	CAP, AL, 470 µF, 10 V, +/- 20%, 0.16 ohm, SMD	SMT Radial F
C12	1	22uF	C3225X7R1C226K250AC	TDK	CAP, CERM, 22 µF, 16 V, +/- 10%, X7R, 1210	1210
C13	1	10uF	EEE-FC1H100P	Panasonic	CAP, AL, 10 μF, 50 V, +/- 20%, 2 ohm, SMD	SMT Radial D
C14, C20, R22, R24, R26, R29, R31, R34	8	DNP	Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference], CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference], RES, xxx ohm, x%, xW, [PackageReference], RES, xxx ohm, x%, xW, [PackageReference], RES, xxx ohm, x%, xW, [PackageReference], RES, xxx ohm, x%, xW, [PackageReference], RES, xxx ohm, x%, xW, [PackageReference], RES, xxx ohm, x%, xW, [PackageReference]	Used in PnP output and some BOM reports
C15	1	0.1uF	C1608X7R1H104K	ТДК	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
C16	1	680pF	C0603C681K5RACTU		CAP, CERM, 680 pF, 50 V, +/- 10%, X7R, 0603	0603
C17	1	0.047uF	C1608X7R1H473K	TDK	CAP, CERM, 0.047 µF, 50 V, +/- 10%, X7R, 0603	0603
C18	1	1uF	08055C105KAT2A	AVX	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 0805	0805
C19	1	560pF	GRM1885C1H561JA01D		CAP, CERM, 560 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C21, C22	2	4700pF	VY2472M49Y5US63V7		CAP, CERM, 4700 pF, 440 V, +/- 20%, Y5U, TH, 12.5x5mm	TH, 12.5x5mm
D1, D3	2	800V	MB8S-TP		Diode, Switching-Bridge, 800 V, 0.5 A, 4-Pin TO269AA, Body 4.95 x 4.2	4-Pin TO269AA, Body
, _ 0	_			-	mm, Pitch 2.555 mm	4.95 x 4.2 mm, Pitch 2.555 mm
D2	1	400V	MURS140-13-F	Diodes Inc.	Diode, Ultrafast, 400 V, 1 A, SMB	SMB
D4	1	28V	MMSZ5255B-7-F	Diodes Inc.	Diode, Zener, 28 V, 500 mW, SOD-123	SOD-123
D5	1	800V	US1K-13-F	Diodes Inc.	Diode, Fast Rectifier, 800 V, 1 A, SMA	SMA
D6	1	100V	MBRS3100T3G	ON Semiconductor	Diode, Schottky, 100 V, 3 A, SMC	SMC
D7	1	200V	BAS21-7-F	Diodes Inc.	Diode, Switching, 200 V, 0.2 A, SOT-23	SOT-23
L1, L2, L3, L4, L5, L6	6	1000uH	7447480102	Wurth Elektronik	Inductor, Wirewound, Ferrite, 470 µH, 1.15 A, 0.47 ohm, TH	TH, Dia 10.5mm
Q1	1		IPD90R1K2C3	Used in BOM report	MOSFET, N-CH, xxV, xxxA, DPAK	Used in PnP output and some BOM reports
R1, R6, R9, R12, R14, R17	6	DNP	Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	0805
R2, R3, R11, R16, R18, R20	6	10.0k	CRCW080510K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.125 W, 0805	0805
R4, R8, R13, R15	4	499k	CRCW1206499KFKEA	Vishay-Dale	RES, 499 k, 1%, 0.25 W, 1206	1206
R5	1	68	CRCW201068R0JNEF	Vishay-Dale	RES, 68, 5%, 0.75 W, 2010	2010
R7	1	100k	CRCW2010100KFKEF	Vishay-Dale	RES, 100 k, 1%, 0.75 W, 2010	2010
R10	1	0	CRCW08050000Z0EAHP	Vishay-Dale	RES, 0, 5%, 0.333 W, 0805	0805
R19	1	10.0	CRCW080510R0FKEA	Vishay-Dale	RES, 10.0, 1%, 0.125 W, 0805	0805
R21	1	0	CRCW06030000Z0EA		RES, 0, 5%, 0.1 W, 0603	0603
R23	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
R25	1	0	CRCW08050000Z0EA		RES, 0, 5%, 0.125 W, 0805	0805

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
R27	1	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0 k, 1%, 0.1 W, 0603	0603
R28	1	2.0k	CRCW06032K00JNEA	Vishay-Dale	RES, 2.0 k, 5%, 0.1 W, 0603	0603
R30	1	499	RT0603DRE07499RL	Yageo America	RES, 499, 0.5%, 0.1 W, 0603	0603
R32	1	60.4k	CRCW060360K4FKEA	Vishay-Dale	RES, 60.4 k, 1%, 0.1 W, 0603	0603
R33	1	0.39	ERJ-8RQFR39V	Panasonic	RES, 0.39, 1%, 0.25 W, 1206	1206
R35	1	5.23k	CRCW06035K23FKEA	Vishay-Dale	RES, 5.23 k, 1%, 0.1 W, 0603	0603
RF1, RF2, RF3	3	10	FW20A10R0JACT-ND	Bourns	RES, 10, 5%, 32W, Fusible, TH, RES, 10, 5%, 2 W, Fusible, TH, RES, 10, 5%, 2 W, Fusible, TH	Axial
RV1, RV2, RV3	3	DNP	S10K275E2	EPCOS Inc	Varistor 275V RMS 10MM Radial, TH	10mm Radial
T1	1	400 uH	750315315	Wurth Elektronik	Transformer, 400 uH, TH	33x26.3mm
TP1, TP2, TP3, TP4, TP5, TP6, TP7	7	Double	1503-2	Keystone	Terminal, Turret, TH, Double	Keystone1503-2
TP8, TP9	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP10	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		LM5021MM-1/NOPB	Texas Instruments	AC-DC Current Mode PWM Controller, 8-pin MSOP, Pb-Free	MUA08A
U2	1		TCMT1107	Vishay-Semiconductor	Optocoupler, 3.75kV RMS, SMT	SOP-4
U3	1		LMV431AIMF/NOPB	Texas Instruments	Low-Voltage (1.24V) Adjustable Precision Shunt Regulators, 3-pin SOT- 23, Pb-Free	MF03A

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